

11. (New) A method of producing a micromechanical sensor arrangement, comprising the steps of:

providing a wafer having a surface and edge areas;
dividing the surface of the wafer into positive areas, to be subsequently etched in a wet chemical etching process, and negative areas including the edge areas of the wafer;
providing the negative areas with a passivation layer to protect the negative areas from the subsequent wet chemical etching process;
etching the wafer in the wet chemical etching process to form a through-hole; and
removing the passivation layer.

12. (New) A method of producing a micromechanical sensor arrangement, comprising the steps of:

providing a wafer having a surface and edge areas;
dividing the surface of the wafer into positive areas, to be subsequently etched in a wet chemical etching process, and negative areas including the edge areas of the wafer;
providing the negative areas with a passivation layer to protect the negative areas from the subsequent wet chemical etching process;
etching the wafer in the wet chemical etching process to form a blind hole; and
removing the passivation layer.

13. (New) A method of producing a micromechanical sensor arrangement, comprising the steps of:

providing a wafer having a surface and edge areas;
dividing the surface of the wafer into positive areas, to be subsequently etched in a wet chemical etching process, and negative areas including the edge areas of the wafer;
providing the negative areas with a passivation layer to protect the negative areas from the subsequent wet chemical etching process;
etching the top surface and the bottom surface of the wafer in the wet chemical etching process; and
removing the passivation layer. --